COMPONENTS MARKED ‘DNP’ SHOULD NOT BE POPULATED.
ASSEMBLY VARIANTS: DDI

<table>
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<th>PCB VIEWED FROM TOP SIDE</th>
<th>BOARD #: PNP21386</th>
<th>REV: A</th>
<th>SUN REV: Not In VersionControl</th>
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PLOT NAME = Top Assembly Drawing
GENERATED: 3/7/2018 4:04:34 PM
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